MICROCHIP Semiconductor Device Type: S2AF / S2AE (4BX) 008 SOIJ/SOIC .208in NiPdAu				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			
		"Contained In"	% Total			89.96	(mg) Total	Mold Compound	% ot Total Weight	66.29
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	00.00			, i	
Silica, vitreous Epoxy Resin (No bromine, No diantimony trioxide)	60676-86-0 Trade Secret	Mold Compound Mold Compound	56.347 4.060	76.462 5.510	563,465 40.603		Silica, vitreous Epoxy Resin	60676-86-0 Trade Secret	85.00 6.13	
Phenolic Resin (No Br / CL SbO3, No diantimony trioxide)	Trade Secret	Mold Compound Mold Compound	4.060	5.510	40,603		Phenolic Resin	Trade Secret	6.13	
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.624	2.204	16,241		Epoxy, Cresol Novolac	29690-82-2	2.45	
Carbon Black	1333-86-4	Mold Compound	0.199	0.270	1.989		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	26.540	36.015	265,403		Gaibbin Black	Total		
Iron	7439-89-6	Lead Frame	0.653	0.886	6,528	37.70	(mg) Total	Lead Frame	% of Total Weight	27.78
Silver	7440-22-4	Lead Frame	0.529	0.718	5,292		Copper	7440-50-8	95.54	1
Zinc	7440-66-6	Lead Frame	0.035	0.047	347		Iron	7439-89-6	2.35	
Phosphorous	7723-14-0	Lead Frame	0.023	0.031	229		Silver	7440-22-4	1.91	
Silver	7440-22-4	Die Attach	0.163	0.221	1,628		Zinc	7440-66-6	0.13	
Epoxy resin	Trade Secret	Die Attach	0.044	0.060	440		Phosphorous	7723-14-0	0.08	
Metal oxide	Trade Secret	Die Attach	0.007	0.009	66			Total	100.00	9
Gamma-butyrolactone	96-48-0	Die Attach	0.007	0.009	66	0.30	(mg) Total	Die Attach	% of Total Weight	0.22
Silicon	7440-21-3	Chip (Die)	5,410	7.341	54,100		Silver	7440-22-4	74.00	1
Gold	7440-57-5	Wire Bond	0.150	0.204	1,500		Epoxy resin	Trade Secret	20.00	
Nickel	7440-02-0	Plating on external leads (pins)(PPF)	0.142	0.192	1,418		Metal oxide	Trade Secret	3.00	
Palladium	7440-05-3	Plating on external leads (pins)(PPF)	0.008	0.010	75		Gamma-butyrolactone	96-48-0	3.00	
Gold	7440-57-5	Plating on external leads (pins)(PPF)	0.001	0.001	8			Total	100.00	1
				105 500	1 000 000	=				
Cold		TOTAL S.	100.000	135.700	1.000.000		Total (mg)	Chip (Die)	% of Total Weight	
emiconductor device and its homogenous materials comply 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without ex	with EU Directives: 20 cemption (zero)		100.000 I (08 June 2011	135.700 ) and 2015/8	1,000,000 63/EU (31	7.34	Total (mg) Doped Silicon	Chip (Die) 7440-21-3 Total	-	
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emiconductor device and its homogenous materials comply 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without ex liance with the above EU Directives has been verified via intr emical substance is absent from the list above, the chemical orated's knowledge and belief as of the date of this docume	with EU Directives: 20 cemption (zero) ernal design controls, s substance is NOT an i nt, there is no credible	g Total Mass 02/95/EC (27 January 2003) & Directive 2011/65/EU supplier declarations, and /or analytical test data. Intentional ingredient in the semiconductor device reason to believe that the unavoidable impurity co	I (08 June 2011 and, to the bes	) and 2015/80 t of Microchi	63/EU (31 p Technology		Doped Silicon	7440-21-3 Total	100.00 I 100.00	
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